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"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Active
Core Processor	ARM® Cortex®-M3
Core Size	32-Bit Single-Core
Speed	32MHz
Connectivity	I ² C, IrDA, LINbus, SPI, UART/USART, USB
Peripherals	Brown-out Detect/Reset, Cap Sense, DMA, I ² S, POR, PWM, WDT
Number of I/O	51
Program Memory Size	512KB (512K x 8)
Program Memory Type	FLASH
EEPROM Size	16K x 8
RAM Size	80K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 21x12b; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	64-LQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/stmicroelectronics/stm32l151ret6

1. Overview

1.1 Outline of Specifications

Table 1.1 shows the outline of the specifications and Table 1.2 shows the comparison of the functions of products in different packages.

Table 1.1 is for products with the greatest number of functions, so numbers of peripheral modules and channels will differ in accord with the package. For details, see Table 1.2, Comparison of Functions for Different Packages.

Table 1.1 Outline of Specifications (1 / 4)

Classification	Module/Function	Description
CPU	CPU	- Maximum operating frequency: 50 MHz 32-bit RX CPU - Minimum instruction execution time: One instruction per state (cycle of the system clock) - Address space: 4-Gbyte linear - Register set - General purpose: Sixteen 32-bit registers - Control: Eight 32-bit registers - Accumulator: One 64-bit register - Basic instructions: 73 - DSP instructions: 9 - Addressing modes: 10 - Data arrangement - Instructions: Little endian - Data: Selectable as little endian or big endian - On-chip 32-bit multiplier: 32 x 32 → 64 bits - On-chip divider: 32 / 32 → 32 bits - Barrel shifter: 32 bits - Memory protection unit (MPU)
Memory	ROM	- Capacity: 256 K/384 K/512 Kbytes 50 MHz, no-wait memory access - On-board programming: 3 types
	RAM	- Capacity: 32 K/64 Kbytes 50 MHz, no-wait memory access
	E2 DataFlash	- Capacity: 8 Kbytes - Number of times for programming/erasing: 100,000
MCU operating mode		Single-chip mode
Clock	Clock generation circuit	- Main clock oscillator, sub-clock oscillator, low-speed on-chip oscillator, high-speed on-chip oscillator, PLL frequency synthesizer, and IWDG-dedicated on-chip oscillator - Oscillation stop detection - Measuring circuit for accuracy of clock frequency (clock-accuracy check: CAC) - Independent settings for the system clock (ICLK), peripheral module clock (PCLK), and FlashIF clock (FCLK) The CPU and system sections such as other bus masters run in synchronization with the system clock (ICLK): 50 MHz (at max.) Peripheral modules run in synchronization with the peripheral module clock (PCLK): 25 MHz (at max.) The flash peripheral circuit runs in synchronization with the flash peripheral clock (FCLK): 25 MHz (at max.)
Reset		RES# pin reset, power-on reset, voltage monitoring reset, watchdog timer reset, independent watchdog timer reset, deep software standby reset, and software reset
Voltage detection	Voltage detection circuit (LVDAa)	- When the voltage on VCC falls below the voltage detection level, an internal reset or internal interrupt is generated. - Voltage detection circuit 0 is capable of selecting the detection voltage from 2 levels - Voltage detection circuit 1 is capable of selecting the detection voltage from 9 levels - Voltage detection circuit 2 is capable of selecting the detection voltage from 9 levels
Low power consumption	Low power consumption facilities	- Module stop function - Four low power consumption modes - Sleep mode, all-module clock stop mode, software standby mode, and deep software standby mode
	Function for lower operating power consumption	High-speed operating mode, middle-speed operating mode 1A, middle-speed operating mode 1B, middle-speed operating mode 2A, middle-speed operating mode 2B, low-speed operating mode 1, low-speed operating mode 2

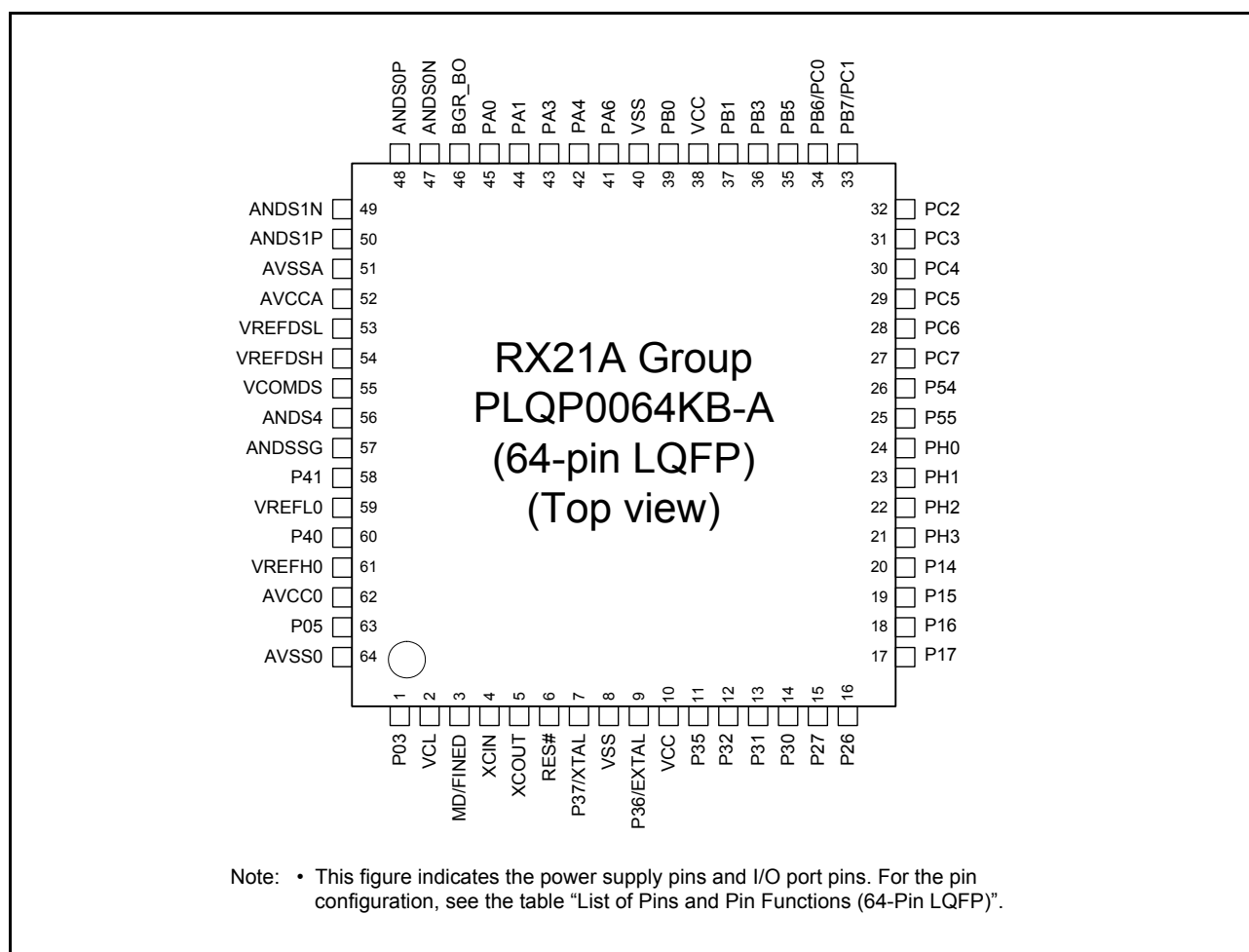


Figure 1.5 Pin Assignments of the 64-Pin LQFP

Table 1.6 List of Pins and Pin Functions (80-Pin LQFP) (2 / 2)

Pin No.	Power Supply, Clock, System Control	I/O Port	Timers (MTU, TMR, POE)	Communications (SCIc, RSPI, RIIC)	Others
42		PB6	MTIOC3D	RXD9/SMISO9/SSCL9	
43		PB5	MTIOC2A/MTIOC1B/TMRI1/POE1#	SCK9	
44		PB4		CTS9#/RTS9#/SS9#	
45		PB3	MTIOC0A/MTIOC4A/TMO0/POE3#	SCK6	
46		PB2		CTS6#/RTS6#/SS6#	
47		PB1	MTIOC0C/MTIOC4C/TMCIO	TXD6/SMOSI6/SSDA6	IRQ4-DS
48	VCC				
49		PB0	MTIC5W	RXD6/SMISO6/SSCL6/RSPCKA	CMPB0
50	VSS				
51		PA6	MTIC5V/MTCLKB/TMC13/POE2#	CTS5#/RTS5#/SS5#/MOSIA	CVREFB0
52		PA5		RSPCKA	
53		PA4	MTIC5U/MTCLKA/TMRI0	TXD5/SMOSI5/SSDA5/IRTXD5/SSLA0	IRQ5-DS/CVREFB1
54		PA3	MTIOC0D/MTCLKD	RXD5/SMISO5/SSCL5/IRRXD5	IRQ6-DS/CMPB1
55		PA2		RXD5/SMISO5/SSCL5/IRRXD5/SSLA3	CMPA2
56		PA1	MTIOC0B/MTCLKC	SCK5/SSLA2	CVREFA
57		PA0	MTIOC4A	SSLA1	CACREF/CMPA1
58	BGR_BO				
59					ANDS0N
60					ANDS0P
61					ANDS1N
62					ANDS1P
63	AVSSA				
64	AVCCA				
65	VREFDSL				
66	VREFDSH				
67	VCOMDS				
68					ANDS4
69					ANDS5
70	ANDSSG				
71		P43			

Table 1.8 List of Pins and Pin Functions (100-Pin TFLGA) (1 / 3)

Pin No.	Power Supply, Clock, System Control	I/O Port	Timers (MTU, TMR, POE)	Communications (SClC, RSPI, RIIC)	Others
A1		P05			AN5/DA1
A2	VREFH				
A3		P07			AN6/ADTRG0#
A4	VREFL0				
A5		P43			AN3
A6	VCOMDS				
A7	AVSSA				
A8					ANDS2N
A9					ANDS1P
A10					ANDS1N
B1		P03			AN4/DA0
B2	AVSS0				
B3	AVCC0				
B4		P40			AN0
B5	ANDSSG				
B6	VREFDSH				
B7	AVCCA				
B8					ANDS3N
B9					ANDS2P
B10					ANDS0P
C1	VCL				
C2	VREFL				
C3		PJ3	MTIOC3C	CTS6#/RTS6#/SS6#	
C4	VREFH0				
C5		P42			AN2
C6					ANDS4
C7	VREFDSL				
C8					ANDS3P
C9	BGR_BO				
C10					ANDS0N
D1	XCIN				
D2	XCOUT				
D3	MD				FINED
D4		PJ1	MTIOC3A		
D5					ANDS6
D6					ANDS5
D7		PE6		MOSIB	IRQ6
D8		PE7		MISOB	IRQ7-DS
D9		PA1	MTIOC0B/MTCLKC	SCK5/SSLA2	CVREFA

2.1 General-Purpose Registers (R0 to R15)

This CPU has sixteen general-purpose registers (R0 to R15). R1 to R15 can be used as data registers or address registers. R0, a general-purpose register, also functions as the stack pointer (SP). The stack pointer is switched to operate as the interrupt stack pointer (ISP) or user stack pointer (USP) by the value of the stack pointer select bit (U) in the processor status word (PSW).

2.2 Control Registers

This CPU has the following eight control registers.

(1) Interrupt Stack Pointer (ISP) / User Stack Pointer (USP)

The stack pointer (SP) can be either of two types, the interrupt stack pointer (ISP) or the user stack pointer (USP). Whether the stack pointer operates as the ISP or USP depends on the value of the stack pointer select bit (U) in the processor status word (PSW).

Set the ISP or USP to a multiple of four, as this reduces the numbers of cycles required to execute interrupt sequences and instructions entailing stack manipulation.

(2) Interrupt Table Register (INTB)

The interrupt table register (INTB) specifies the address where the relocatable vector table starts.

(3) Program Counter (PC)

The program counter (PC) indicates the address of the instruction being executed.

(4) Processor Status Word (PSW)

The processor status word (PSW) indicates the results of instruction execution or the state of the CPU.

(5) Backup PC (BPC)

The backup PC (BPC) is provided to speed up response to interrupts.

After a fast interrupt has been generated, the contents of the program counter (PC) are saved in the BPC register.

(6) Backup PSW (BPSW)

The backup PSW (BPSW) is provided to speed up response to interrupts.

After a fast interrupt has been generated, the contents of the processor status word (PSW) are saved in the BPSW. The allocation of bits in the BPSW corresponds to that in the PSW.

(7) Fast Interrupt Vector Register (FINTV)

The fast interrupt vector register (FINTV) is provided to speed up response to interrupts.

The FINTV register specifies a branch destination address when a fast interrupt has been generated.

2.3 Register Associated with DSP Instructions

(1) Accumulator (ACC)

The accumulator (ACC) is a 64-bit register used for DSP instructions. The accumulator is also used for the multiply and multiply-and-accumulate instructions; EMUL, EMULU, MUL, and RMPA, in which case the prior value in the accumulator is modified by execution of the instruction.

Use the MVTACHI and MVTACLO instructions for writing to the accumulator. The MVTACHI and MVTACLO instructions write data to the higher-order 32 bits (bits 63 to 32) and the lower-order 32 bits (bits 31 to 0), respectively. Use the MVFACHI and MVFACMI instructions for reading data from the accumulator. The MVFACHI and MVFACMI instructions read data from the higher-order 32 bits (bits 63 to 32) and the middle 32 bits (bits 47 to 16), respectively.

3. Address Space

3.1 Address Space

This LSI has a 4-Gbyte address space, consisting of the range of addresses from 0000 0000h to FFFF FFFFh. That is, linear access to an address space of up to 4 Gbytes is possible, and this contains both program and data areas.

Figure 3.1 shows the memory map.

4. I/O Registers

This section provides information on the on-chip I/O register addresses and bit configuration. The information is given as shown below. Notes on writing to registers are also given below.

(1) I/O register addresses (address order)

- Registers are listed from the lower allocation addresses.
- Registers are classified according to module symbols.
- Numbers of cycles for access indicate numbers of cycles of the given base clock.
- Among the internal I/O register area, addresses not listed in the list of registers are reserved. Reserved addresses must not be accessed. Do not access these addresses; otherwise, the operation when accessing these bits and subsequent operations cannot be guaranteed.

(2) Notes on writing to I/O registers

When writing to an I/O register, the CPU starts executing the subsequent instruction before completing I/O register write. This may cause the subsequent instruction to be executed before the post-update I/O register value is reflected on the operation.

As described in the following examples, special care is required for the cases in which the subsequent instruction must be executed after the post-update I/O register value is actually reflected.

[Examples of cases requiring special care]

- The subsequent instruction must be executed while an interrupt request is disabled with the IENj bit in IERN of the ICU (interrupt request enable bit) cleared to 0.
- A WAIT instruction is executed immediately after the preprocessing for causing a transition to the low power consumption state.

In the above cases, after writing to an I/O register, wait until the write operation is completed using the following procedure and then execute the subsequent instruction.

- Write to an I/O register.
- Read the value from the I/O register to a general register.
- Execute the operation using the value read.
- Execute the subsequent instruction.

[Instruction examples]

- Byte-size I/O registers

```
MOV.L #SFR_ADDR, R1
MOV.B #SFR_DATA, [R1]
CMP [R1].UB, R1
;; Next process
```

- Word-size I/O registers

```
MOV.L #SFR_ADDR, R1
MOV.W #SFR_DATA, [R1]
CMP [R1].W, R1
;; Next process
```

Table 4.1 List of I/O Registers (Address Order) (9 / 24)

Address	Module Symbol	Register Name	Register Symbol	Number of Bits	Access Size	Number of Access Cycles	
						ICLK $\geq$ PCLK	ICLK < PCLK
0008 73E2h	ICU	Interrupt source priority register 226	IPR226	8	8		2 ICLK
0008 73E6h	ICU	Interrupt source priority register 230	IPR230	8	8		2 ICLK
0008 73EAh	ICU	Interrupt source priority register 234	IPR234	8	8		2 ICLK
0008 73F6h	ICU	Interrupt source priority register 246	IPR246	8	8		2 ICLK
0008 73F7h	ICU	Interrupt source priority register 247	IPR247	8	8		2 ICLK
0008 73F8h	ICU	Interrupt source priority register 248	IPR248	8	8		2 ICLK
0008 73F9h	ICU	Interrupt source priority register 249	IPR249	8	8		2 ICLK
0008 73FAh	ICU	Interrupt source priority register 250	IPR250	8	8		2 ICLK
0008 73FBh	ICU	Interrupt source priority register 251	IPR251	8	8		2 ICLK
0008 73FCh	ICU	Interrupt source priority register 252	IPR252	8	8		2 ICLK
0008 73FDh	ICU	Interrupt source priority register 253	IPR253	8	8		2 ICLK
0008 7400h	ICU	DMAC activation request select register 0	DMRSR0	8	8		2 ICLK
0008 7404h	ICU	DMAC activation request select register 1	DMRSR1	8	8		2 ICLK
0008 7408h	ICU	DMAC activation request select register 2	DMRSR2	8	8		2 ICLK
0008 740Ch	ICU	DMAC activation request select register 3	DMRSR3	8	8		2 ICLK
0008 7500h	ICU	IRQ control register 0	IRQCR0	8	8		2 ICLK
0008 7501h	ICU	IRQ control register 1	IRQCR1	8	8		2 ICLK
0008 7502h	ICU	IRQ control register 2	IRQCR2	8	8		2 ICLK
0008 7503h							

Table 4.1 List of I/O Registers (Address Order) (10 / 24)

Address	Module Symbol	Register Name	Register Symbol	Number of Bits	Access Size	Number of Access Cycles	
						ICLK $\geq$ PCLK	ICLK < PCLK
0008 8034h	IWDT	IWDT status register	IWDTSR	16	16	2, 3 PCLKB	2 ICLK
0008 8036h	IWDT	IWDT reset control register	IWDTRCR	8	8	2, 3 PCLKB	2 ICLK
0008 8038h	IWDT	IWDT count stop control register	IWDTCTPR	8	8	2, 3 PCLKB	2 ICLK
0008 80C0h	DA	D/A data register 0	DADR0	16	16	2, 3 PCLKB	2 ICLK
0008 80C2h	DA	D/A data register 1	DADR1	16	16	2, 3 PCLKB	2 ICLK
0008 80C4h	DA	D/A control register	DACR	8	8	2, 3 PCLKB	2 ICLK
0008 80C5h	DA	DADRM format select register	DADPR	8	8	2, 3 PCLKB	2 ICLK
0008 8200h	TMR0	Timer control register	TCR	8	8	2, 3 PCLKB	2 ICLK
0008 8201h	TMR1	Timer counter control register	TCR	8	8	2, 3 PCLKB	2 ICLK
0008 8202h	TMR0	Timer control/status register	TCSR	8	8	2, 3 PCLKB	2 ICLK
0008 8203h	TMR1	Timer control/status register	TCSR	8	8	2, 3 PCLKB	2 ICLK
0008 8204h	TMR0	Time constant register A	TCORA	8	8	2, 3 PCLKB	2 ICLK
0008 8205h	TMR1	Time constant register A	TCORA	8	8 ^{*1}	2, 3 PCLKB	2 ICLK
0008 8206h	TMR0	Time constant register B	TCORB	8	8	2, 3 PCLKB	2 ICLK
0008 8207h	TMR1	Time constant register B	TCORB	8	8 ^{*1}	2, 3 PCLKB	2 ICLK
0008 8208h	TMR0	Timer counter	TCNT	8	8	2, 3 PCLKB	2 ICLK
0008 8209h	TMR1	Timer counter	TCNT	8	8 ^{*1}	2, 3 PCLKB	2 ICLK
00							

Table 4.1 List of I/O Registers (Address Order) (16 / 24)

Address	Module Symbol	Register Name	Register Symbol	Number of Bits	Access Size	Number of Access Cycles	
						ICLK $\geq$ PCLK	ICLK < PCLK
0008 A108h	SCI8	Noise filter setting register	SNFR	8	8	2, 3 PCLKB	2 ICLK
0008 A109h	SCI8	I ² C mode register 1	SIMR1	8	8	2, 3 PCLKB	2 ICLK
0008 A10Ah	SCI8	I ² C mode register 2	SIMR2	8	8	2, 3 PCLKB	2 ICLK
0008 A10Bh	SCI8	I ² C mode register 3	SIMR3	8	8	2, 3 PCLKB	2 ICLK
0008 A10Ch	SCI8	I ² C status register	SISR	8	8	2, 3 PCLKB	2 ICLK
0008 A10Dh	SCI8	SPI mode register	SPMR	8	8	2, 3 PCLKB	2 ICLK
0008 A120h	SCI9	Serial mode register	SMR	8	8	2, 3 PCLKB	2 ICLK
0008 A121h	SCI9	Bit rate register	BRR	8	8	2, 3 PCLKB	2 ICLK
0008 A122h	SCI9	Serial control register	SCR	8	8	2, 3 PCLKB	2 ICLK
0008 A123h	SCI9	Transmit data register	TDR	8	8	2, 3 PCLKB	2 ICLK
0008 A124h	SCI9	Serial status register	SSR	8	8	2, 3 PCLKB	2 ICLK
0008 A125h	SCI9	Receive data register	RDR	8	8	2, 3 PCLKB	2 ICLK
0008 A126h	SCI9	Smart card mode register	SCMR	8	8	2, 3 PCLKB	2 ICLK
0008 A127h	SCI9	Serial extended mode register	SEMR	8	8	2, 3 PCLKB	2 ICLK
0008 A128h	SCI9	Noise filter setting register	SNFR	8	8	2, 3 PCLKB	2 ICLK
0008 A129h	SCI9	I ² C mode register 1	SIMR1	8	8	2, 3 PCLKB	2 ICLK
0008 A12Ah	SCI9	I ² C mode register 2	SIMR2	8	8	2, 3 PCLKB	2 ICLK
0008 A12Bh	SCI9	I ²					

Table 4.1 List of I/O Registers (Address Order) (18 / 24)

Address	Module Symbol	Register Name	Register Symbol	Number of Bits	Access Size	Number of Access Cycles	
						ICLK $\geq$ PCLK	ICLK < PCLK
0008 B444h	DSAD	$\Delta\Sigma$ A/D data register 3	DSADDR3	32	32	2, 3 PCLKB	2 ICLK
0008 B448h	DSAD	$\Delta\Sigma$ A/D input select register 3	DSADISR3	8	8	2, 3 PCLKB	2 ICLK
0008 B450h	DSAD	$\Delta\Sigma$ A/D control register 4	DSADCR4	8	8	2, 3 PCLKB	2 ICLK
0008 B451h	DSAD	$\Delta\Sigma$ A/D control/status register 4	DSADCSR4	8	8	2, 3 PCLKB	2 ICLK
0008 B452h	DSAD	$\Delta\Sigma$ A/D gain select register 4	DSADGSR4	8	8	2, 3 PCLKB	2 ICLK
0008 B453h	DSAD	$\Delta\Sigma$ A/D overwrite flag register 4	DSADFR4	8	8	2, 3 PCLKB	2 ICLK
0008 B454h	DSAD	$\Delta\Sigma$ A/D data register 4	DSADDR4	32	32	2, 3 PCLKB	2 ICLK
0008 B458h	DSAD	$\Delta\Sigma$ A/D input select register 4	DSADISR4	8	8	2, 3 PCLKB	2 ICLK
0008 B460h	DSAD	$\Delta\Sigma$ A/D control register 5	DSADCR5	8	8	2, 3 PCLKB	2 ICLK
0008 B461h	DSAD	$\Delta\Sigma$ A/D control/status register 5	DSADCSR5	8	8	2, 3 PCLKB	2 ICLK
0008 B462h	DSAD	$\Delta\Sigma$ A/D gain select register 5	DSADGSR5	8	8	2, 3 PCLKB	2 ICLK
0008 B463h	DSAD	$\Delta\Sigma$ A/D overwrite flag register 5	DSADFR5	8	8	2, 3 PCLKB	2 ICLK
0008 B464h	DSAD	$\Delta\Sigma$ A/D data register 5	DSADDR5	32	32	2, 3 PCLKB	2 ICLK
0008 B468h	DSAD	$\Delta\Sigma$ A/D input select register 5	DSADISR5	8	8	2, 3 PCLKB	2 ICLK
0008 B470h	DSAD	$\Delta\Sigma$ A/D control register 6	DSADCR6	8	8	2, 3 PCLKB	2 ICLK

Item					Symbol	Typ.	Max.	Unit	Test Conditions
Supply current*1	Low-speed operating mode 1	Normal operating mode	No peripheral operation*6	ICLK = 8 MHz	I _{CC}	1.9	—	mA	
				ICLK = 4 MHz		1.2	—		
			All peripheral operation: Normal*7	ICLK = 8 MHz		2.5	—		
				ICLK = 4 MHz		1.7	—		
		Sleep mode	No peripheral operation	ICLK = 8 MHz		—	12		
				ICLK = 4 MHz		1.3	—		
			All peripheral operation: Normal	ICLK = 8 MHz		0.9	—		
				ICLK = 4 MHz		1.9	—		
		All-module clock stop mode		ICLK = 8 MHz		1.3	—		
				ICLK = 4 MHz		1.1	—		
	Low-speed operating mode 2	Normal operating mode	No peripheral operation*9	ICLK = 32 kHz		0.9	—		
				ICLK = 4 MHz		0.027	—		
			All peripheral operation: Normal*10	ICLK = 32 kHz		0.030	—		
		Sleep mode	No peripheral operation	ICLK = 32 kHz		—	1.0		
				ICLK = 32 kHz		0.022	—		

5.2.2 Standard I/O Pin Output Characteristics (2)

Figure 5.16 to Figure 5.20 show the characteristics when high-drive output is selected by the drive capacity control register.

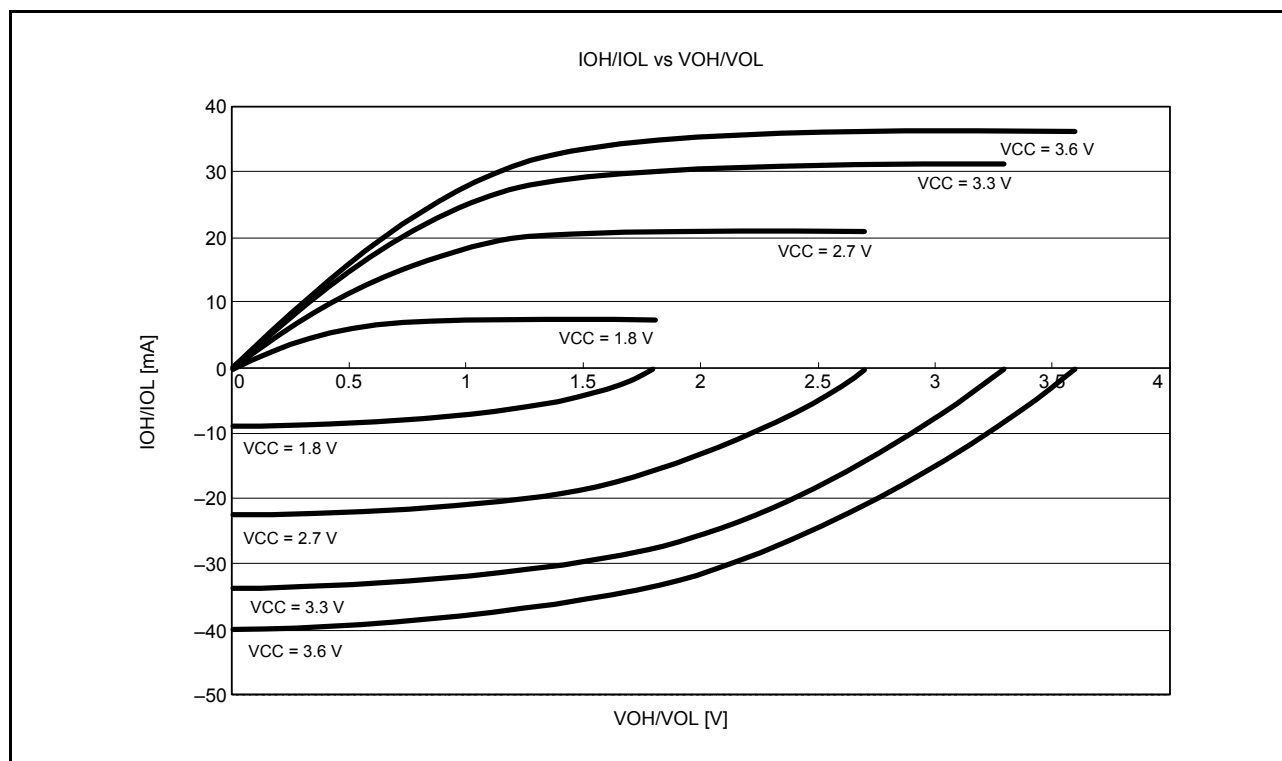


Figure 5.16 V_{OH}/V_{OL} and I_{OH}/I_{OL} Voltage Characteristics at $T_a = 25^\circ\text{C}$ when High-Drive Output is Selected (Reference Data)

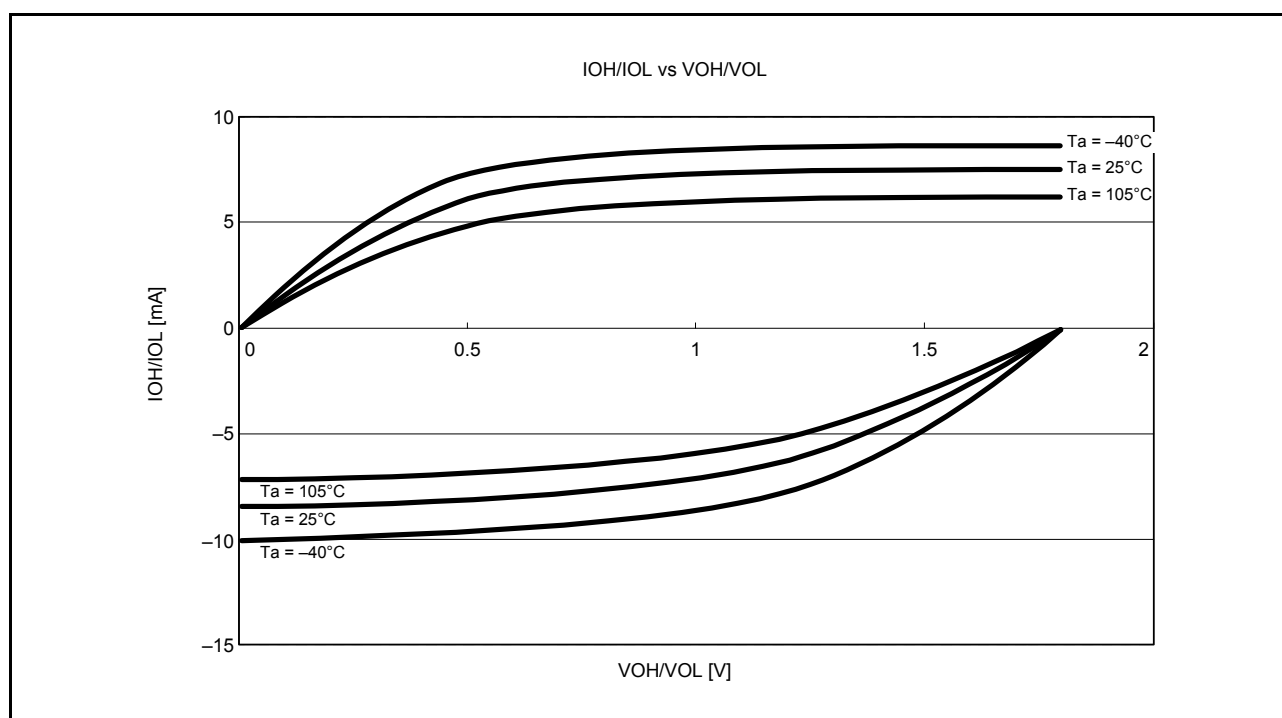


Figure 5.17 V_{OH}/V_{OL} and I_{OH}/I_{OL} Temperature Characteristics at $V_{CC} = 1.8\text{ V}$ when High-Drive Output is Selected (Reference Data)

- Note 2. When specifying the main clock oscillator stabilization time, load MOSCWTCR register with a stabilization time value that is greater than the resonator-vendor-recommended value. When determining the main lock oscillation stabilization wait time, allow an adequate margin (2 times is recommended) for the main clock oscillation stabilization time. Start using the main clock in the main clock oscillation stabilization wait time ($t_{\text{MAINOSCWT}}$) after setting up the main clock oscillator for operation with the MOSCCR.MOSTP bit. The indicated value is a reference value that is measured for an 8 MHz resonator.
- Note 3. Sum of the main clock oscillation stabilization time and the PLL oscillation stabilization time.
- Note 4. The indicated value is a reference value that is measured for an 8 MHz resonator.
- Note 5. When specifying the sub-clock oscillation stabilization time, load SOSCWTCR register with a stabilization time value that is greater than the resonator-vendor-recommended value. When determining the sub-clock oscillation stabilization wait time, allow an adequate margin (2 times is recommended) for the sub-clock oscillation stabilization time. Start using the sub-clock in the sub-clock oscillation stabilization wait time (t_{SUBOSCWT}) after setting up the sub-clock oscillator for operation with the SOSCCR.SOSTP or RCR3.RTCEN bit.

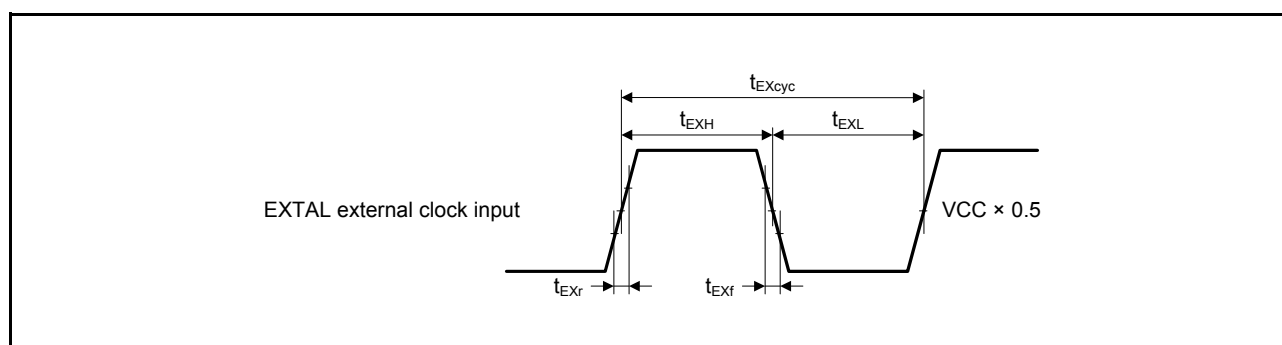


Figure 5.25 EXTAL External Clock Input Timing

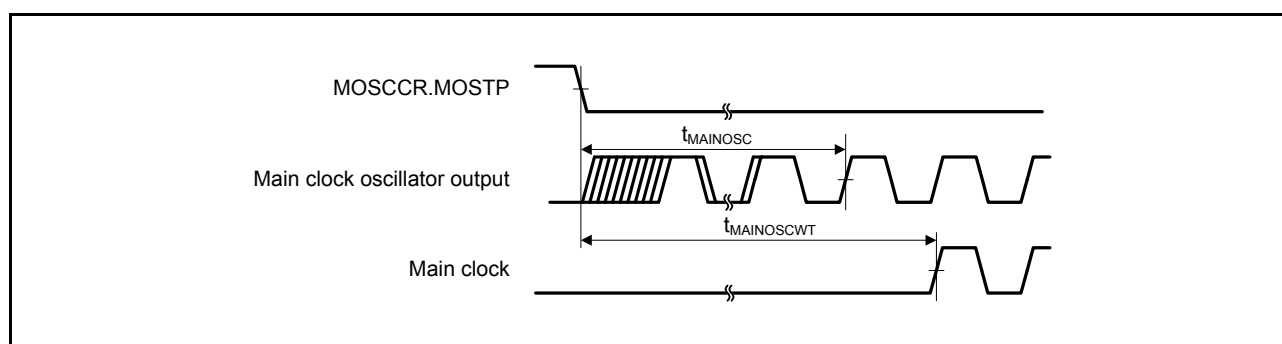


Figure 5.26 Main Clock Oscillation Start Timing

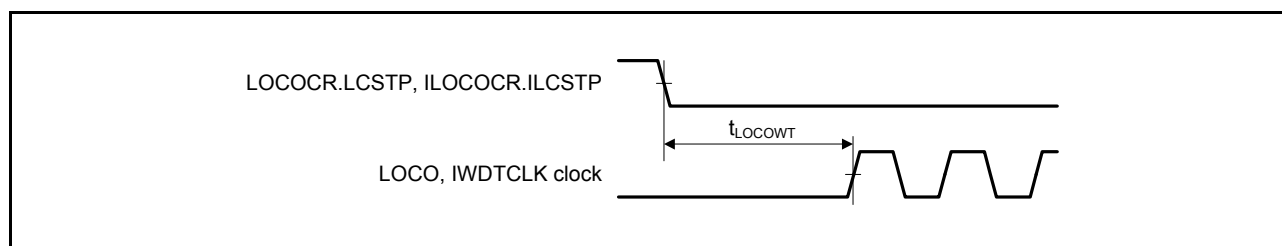


Figure 5.27 LOCO, IWDTCCLK Clock Oscillation Start Timing

Table 5.34 Timing of On-Chip Peripheral Modules (5)

Conditions: $V_{CC} = AV_{CC0} = AV_{CCA} = 2.7$ to 3.6 V, $V_{SS} = AV_{SS0} = AV_{SSA} = V_{REFL} = V_{REFL0} = V_{REFDSL} = 0$ V,
 $T_a = -40$ to $+105^{\circ}\text{C}$

Item		Symbol	Min.*1, *2	Max.	Unit	Test Conditions
RIIC (Standard mode, SMBus)	SCL input cycle time	t_{SCL}	$6 (12) \times t_{IICcyc} + 1300$	—	ns	Figure 5.54
	SCL input high pulse width	t_{SCLH}	$3 (6) \times t_{IICcyc} + 300$	—	ns	
	SCL input low pulse width	t_{SCLL}	$3 (6) \times t_{IICcyc} + 300$	—	ns	
	SCL, SDA input rise time	t_{Sr}	—	1000	ns	
	SCL, SDA input fall time	t_{Sf}	—	300	ns	
	SCL, SDA input spike pulse removal time	t_{SP}	0	$1 (4) \times t_{IICcyc}$	ns	
	SDA input bus free time	t_{BUF}	$3 (6) \times t_{IICcyc} + 300$	—	ns	
	Start condition input hold time	t_{STAH}	$t_{IICcyc} + 300$	—	ns	
	Restart condition input setup time	t_{STAS}	1000	—	ns	
	Stop condition input setup time	t_{STOS}	1000	—	ns	
	Data input setup time	t_{SDAS}	$t_{IICcyc} + 50$	—	ns	
	Data input hold time	t_{SDAH}	0	—	ns	
	SCL, SDA capacitive load	C_b	—	400	pF	
RIIC (Fast mode)	SCL input cycle time	t_{SCL}	$6 (12) \times t_{IICcyc} + 600$	—	ns	Figure 5.54
	SCL input high pulse width	t_{SCLH}	$3 (6) \times t_{IICcyc} + 300$	—	ns	
	SCL input low pulse width	t_{SCLL}	$3 (6) \times t_{IICcyc} + 300$	—	ns	

Table 5.35 Timing of On-Chip Peripheral Modules (6)

Conditions: $V_{CC} = AVCC0 = AVCCA = 2.7$ to 3.6 V, $V_{SS} = AVSS0 = AVSSA = VREFL = VREFL0 = VREFDSL = 0$ V,
 $T_a = -40$ to $+105^{\circ}\text{C}$

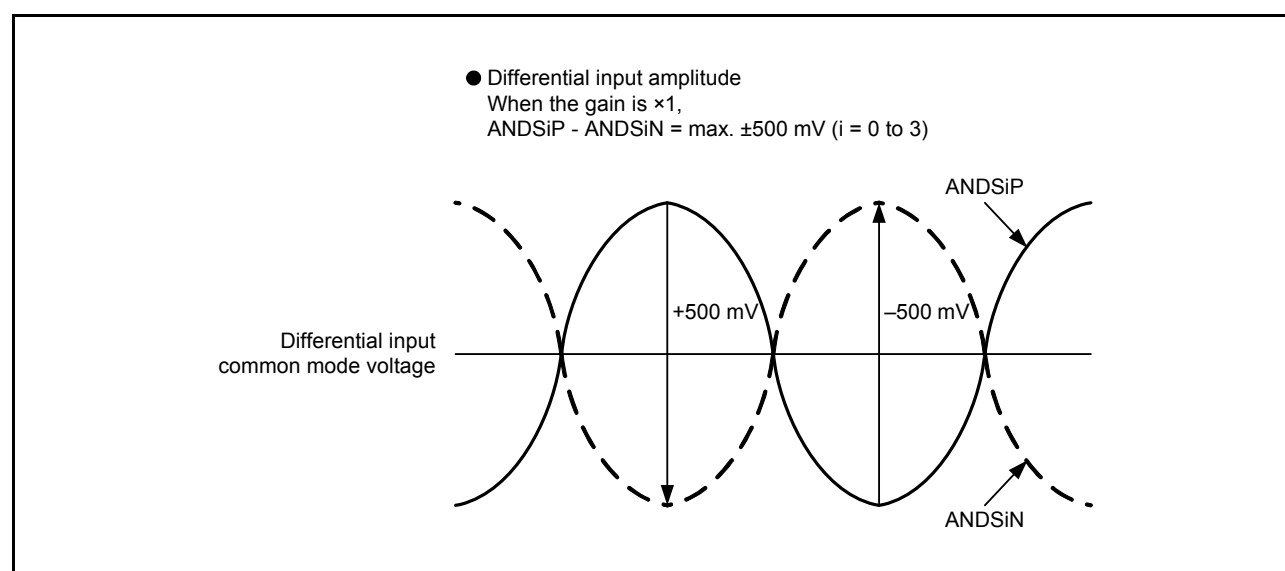
Item		Symbol	Min.*1	Max.	Unit	Test Conditions
Simple IIC (Standard mode)	SDA input rise time	t_{Sr}	—	1000	ns	Figure 5.54
	SDA input fall time	t_{Sf}	—	300	ns	
	SDA input spike pulse removal time	t_{SP}	0	$4 \times t_{pcyc}^{*2}$	ns	
	Data input setup time	t_{SDAS}	250	—	ns	
	Data input hold time	t_{SDAH}	0	—	ns	
	SCL, SDA capacitive load	C_b	—	400	pF	
Simple IIC (Fast mode)	SDA input rise time	t_{Sr}	$20 + 0.1C_b$	300	ns	Figure 5.54
	SDA input fall time	t_{Sf}	$20 + 0.1C_b$	300	ns	
	SDA input spike pulse removal time	t_{SP}	0	$4 \times t_{pcyc}^{*2}$	ns	
	Data input setup time	t_{SDAS}	100	—	ns	
	Data input hold time	t_{SDAH}	0	—	ns	
	SCL, SDA capacitive load	C_b	—	400	pF	

Note: • t_{pcyc} : PCLK cycle

Note 1. C_b indicates the total capacity of the bus line.

Note 2. This applies when the SMR.CKS[1:0] bits = 00b and the SNFR.NFCS[2:0] bits = 010b while the SNFR.NFE bit = 1 and the digital filter is enabled.

Item	Min.	Typ.	Max.	Unit	Test Conditions	
Input impedance for single-ended input ($\times 4$)	54	91	—	k Ω		
Oversampling frequency	3.125	3.125	3.125	MHz		
Oversampling period	0.32	0.32	0.32	μ s		
Conversion time	81.92	—	245.76	μ s		
Sampling frequency	4.07	—	12.21	kHz		
SNDR (Gain: $\times 1$ Input amplitude: 500.0 mV)	—	80	—	dB		Sampling frequency = 12.21 kHz Clock source: Resonator
	—	85	—	dB	Bandwidth = up to 1.7 kHz	
SNDR (Gain: $\times 2$ Input amplitude: 250.0 mV)	—	80	—	dB		
	—	85	—	dB	Bandwidth = up to 1.7 kHz	
SNDR (Gain: $\times 4$ Input amplitude: 125.0 mV)	—	78	—	dB		
	—	83	—	dB	Bandwidth = up to 1.7 kHz	
SNDR (Gain: $\times 8$ Input amplitude: 62.5 mV)	—	75	—	dB		
	—	80	—	dB	Bandwidth = up to 1.7 kHz	
SNDR (Gain: $\times 16$ Input amplitude: 31.2 mV)	—	71	—	dB		
	—	76	—	dB	Bandwidth = up to 1.7 kHz	
SNDR (Gain: $\times 32$ Input amplitude: 14.4 mV)	—	64	—	dB		
	—	69	—	dB	Bandwidth = up to 1.7 kHz	
SNDR (Gain: $\times 64$ Input amplitude: 5 mV)	—	54	—	dB		
	—	59	—	dB	Bandwidth = up to 1.7 kHz	



Differential nonlinearity error (DNL)

Differential nonlinearity error is the difference between 1-LSB width based on the ideal A/D conversion characteristics and the width of the actually output code.

Offset error

Offset error is the difference between a transition point of the ideal first output code and the actual first output code.

Full-scale error

Full-scale error is the difference between a transition point of the ideal last output code and the actual last output code.

5.11 Oscillation Stop Detection Timing

Table 5.46 Oscillation Stop Detection Circuit Characteristics

Conditions: $V_{CC} = AVCC0 = AVCCA = 1.8$ to 3.6 V, $V_{SS} = AVSS0 = AVSSA = VREFL = VREFL0 = VREFDSL = 0$ V,
 $T_a = -40$ to $+105^{\circ}\text{C}$

Item	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Detection time	t_{dr}	—	—	1	ms	Figure 5.69

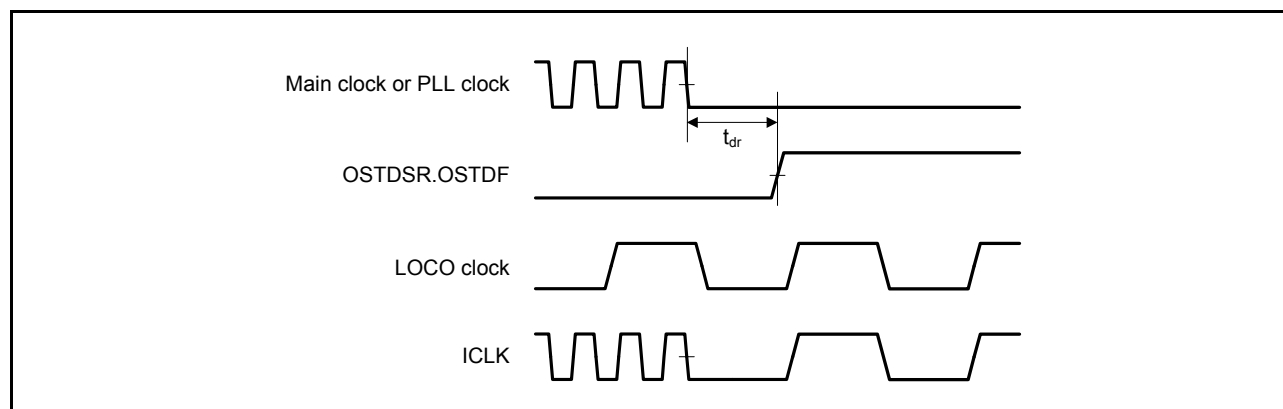


Figure 5.69 Oscillation Stop Detection Timing

**Table 5.49 ROM (Flash Memory for Code Storage) Characteristics (3)
: medium-speed operating modes 1B and 2B**

Conditions: $V_{CC} = AV_{CC0} = AV_{CCA} = 1.8$ to 3.6 V, $V_{SS} = AV_{SS0} = AV_{SSA} = V_{REFL} = V_{REFL0} = V_{REFDSL} = 0$ V
 Temperature range for the programming/erasure operation: $T_a = -40$ to $+105^{\circ}\text{C}$

Item		Symbol	FCLK = 4 MHz			FCLK = 25 MHz*1			Unit
			Min.	Typ.	Max.	Min.	Typ.	Max.	
Programming time when $N_{PEC} \leq 100$ times	2 bytes	t_{P2}	—	0.25	5.0	—	0.21	2.9	ms
	8 bytes	t_{P8}	—	0.25	5.3	—	0.21	3.1	
	128 bytes	t_{P128}	—	0.92	14.0	—	0.66	8.5	
Programming time when $N_{PEC} > 100$ times	2 bytes	t_{P2}	—	0.31	6.2	—	0.26	3.6	ms
	8 bytes	t_{P8}	—	0.31	6.6	—	0.26	3.8	
	128 bytes	t_{P128}	—	1.09	17.5	—	0.78	10.3	
Erasure time when $N_{PEC} \leq 100$ times	2 Kbytes	t_{E2K}	—	21.0	113.6	—	18.6	48.7	ms
Erasure time when $N_{PEC} > 100$ times	2 Kbytes	t_{E2K}	—	25.6	220.6	—	22.7	94.5 (1000 times $\geq N_{PEC} > 100$ times), 102.9 (10000 times $\geq N_{PEC} > 1000$ times)	ms
Suspend delay time during programming (in programming/erasure priority mode)		t_{SPD}	—	—	1.7	—	—	1.604	ms
First suspend delay time during programming (in suspend priority mode)		t_{SPSD1}	—	—	220	—	—	124	μs
Second suspend delay time during programming (in suspend priority mode)		t_{SPSD2}	—	—	1.7				